CSM Series

Board Mount Heat Sink For TO-220 Devices



The economically priced CSM Series is suitable for use with TO-220 devices found in active components as well as power resistors. With surface areas ranging from 1188 Sq. mm to 6645 Sq. mm, the CSM family comes in 5 configurations, all of them with Black Anodized surface treatment. These heatsinks offer a range of thermal performance from 18.0 to 9.8 C/W. Each device offers solder able mounting feet and anywhere from 1, 2 or 3 mounting holes are available for convenient device attachment.

SERIES SPECIFICATIONS

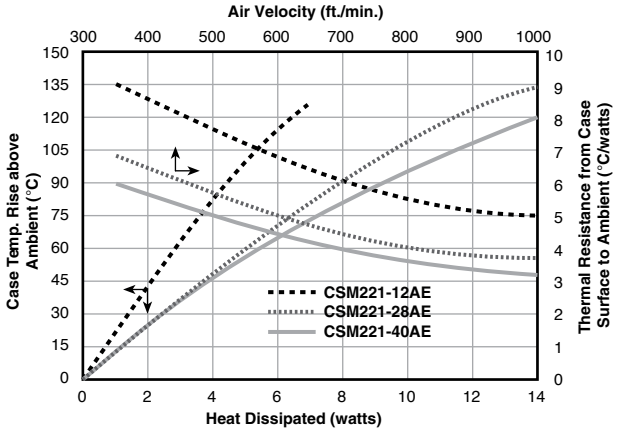
Heatsink Part Number	Surface Area (in^2 / mm^2)	Weight (oz / g)	Length L (mm)	Thermal Res.* (°C/W)
CSM221-12AE	1.84 / 1,188	0.13/ 3.7	12	18.0
CSM221-28AE	4.30 / 2,772	0.3 / 8.5	28	12.8
CSM221-40AE	6.14 / 3,960	0.43 / 12.2	40	12.1
CSM222-30AE	6.25 / 4,029	0.5 / 14.2	30	11.3
CSM223-50AE	10.30 / 6,645	0.6 / 17.0	50	9.8

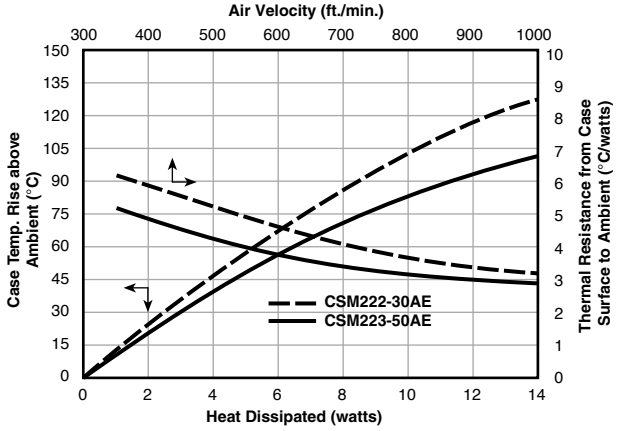
*Free convection at 10 watts dissipation

CHARACTERISTICS

Heat Dissipation

Heat dissipation is the total for ALL DEVICES attached to the heat sink





Heat Sink	Aluminum Alloy 6063-T5 or Equivalent with either degreased or black anodized finish.
Solder Foot	Cold-rolled Steel, surface tin plated.
Interface Thermal Resistance	for improvement, use thermal joint compound, 0.005 Grafoil (TGon 800 by Laird), or phase change material (Hi-Flow by Bergquist)
Insulator	(Optional) Sil-Pad 900-S, K6 800-S and K10 by Bergquist

(continued)

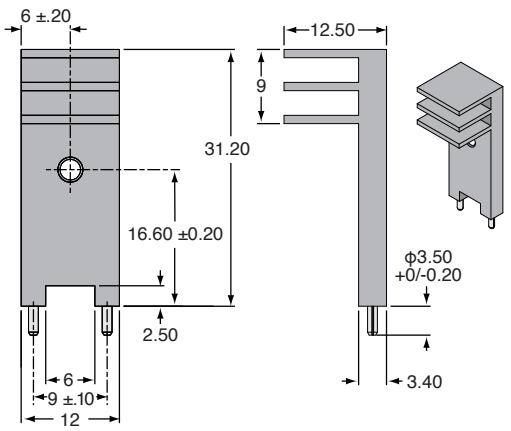
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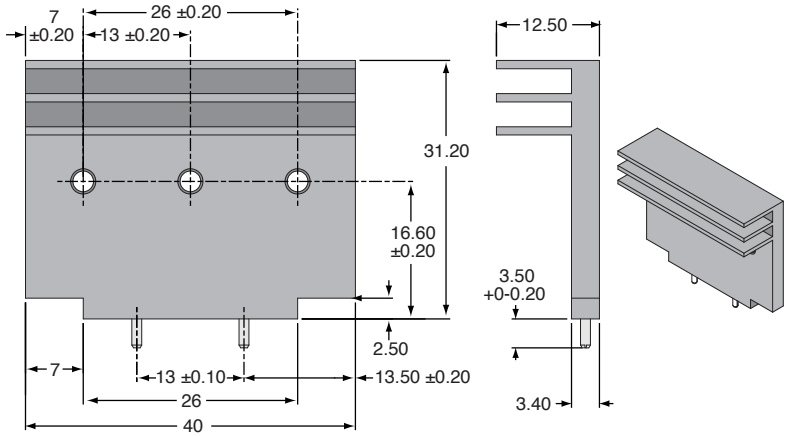
DIMENSIONS

Dimensions in mm; M3*0.5P thread Tapping. JIS-2b standard chamfer 0.3m

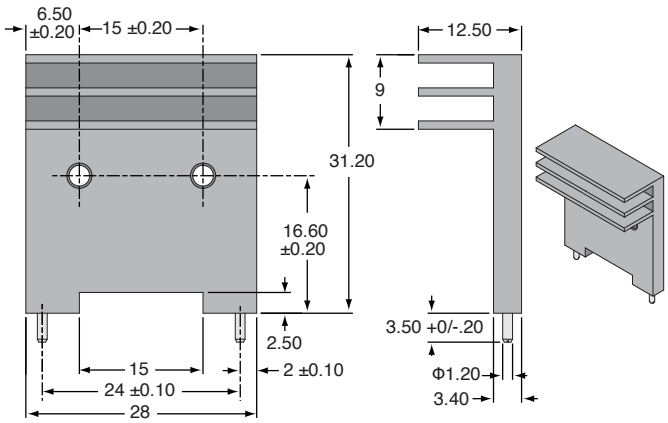
CSM221-12AE



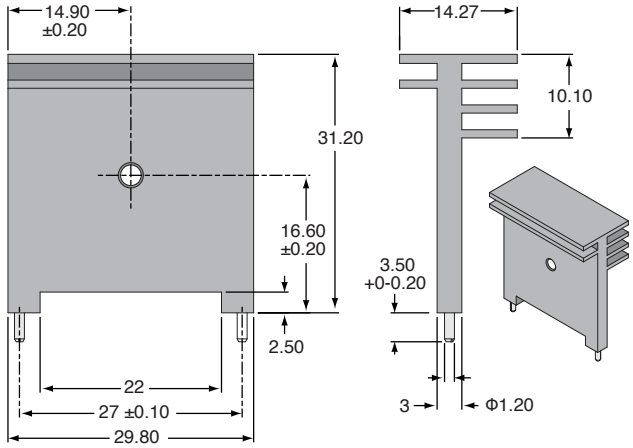
CSM221-40AE



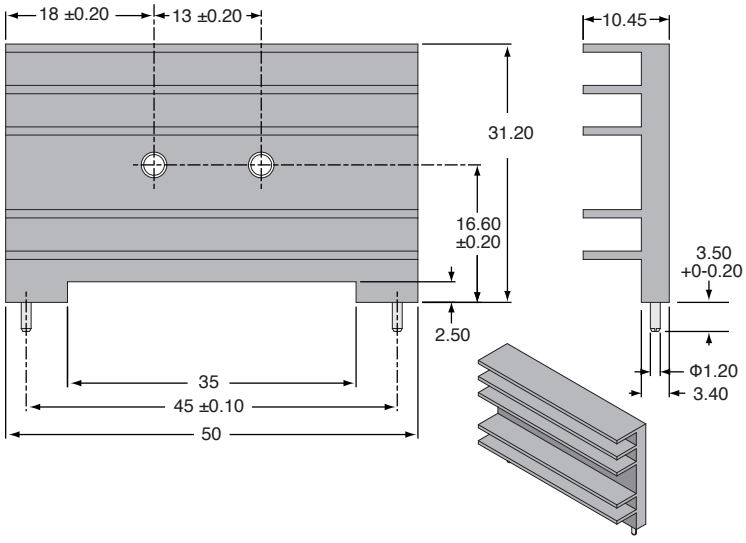
CSM221-28AE



CSM222-30AE



CSM223-50AE



HOW TO ORDER

RoHS Compliant

C S M 2 2 1 - 1 2 A E

Series	Extrusion type	Extrusion width	Black anodized